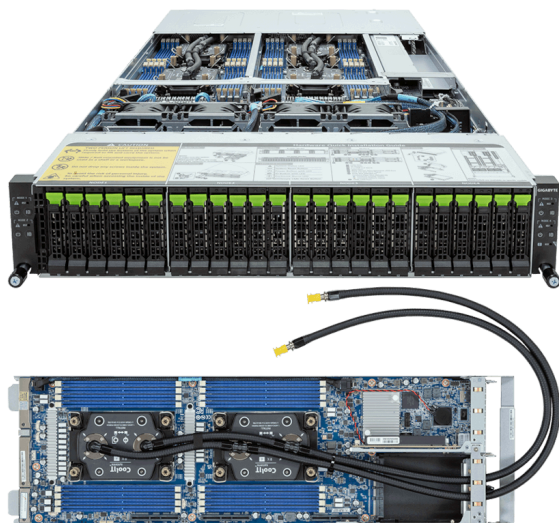


H263-S62-LAW1

High Density Server - 5th/4th Gen Intel® Xeon® Scalable -
2U 4-Node DP 24-Bay Gen4 NVMe/SATA/SAS 3000W DLC



Key Features

- Direct liquid cooling solution
- 2U 4-node rear access server system
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors per node
- Dual Intel® Xeon® CPU Max Series per node
- 8-Channel DDR5 RDIMM, 16 x DIMMs per node
- 1 x CMC port
- 24 x 2.5" Gen4 NVMe/SATA/SAS hot-swap bays
- 4 x M.2 slots with PCIe Gen4 x4 interface **(optional)**
- 4 x LP PCIe Gen5 x16 slots
- 4 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

Applications

High-Performance Computing Server, High Converged Server...

Specification

Dimensions	2U 4-Node - Rear access (W440 x H87.5 x D850 mm)	PCIe Expansion Slots	4 x LP PCIe Gen5 x16 4 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
Motherboard	MS63-HD1	I/O Ports	Front: 1 x CMC status LED, 1 x CMC reset button Rear: 8 x USB 3.2 Gen1, 4 x VGA, 4 x MLAN, 1 x CMC
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor per node, TDP up to 385W	Backplane Board	PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
OS Compatibility	OS Support List	TPM	1 x TPM header (SPI), Optional TPM2.0 kit: CTM010
Socket	8 x LGA 4677 (Socket E)	Power Supply	Dual 3000W 80 PLUS Titanium redundant power supply Available for 2+1 redundant power supply configuration (optional) AC Input: 100-240V *The system power supply requires C19 power cord.
Chipset	Intel® C741	System Fans	4 x 80x80x38mm
Memory	8-Channel DDR5 RDIMM, 64 x DIMMs [5th Gen Intel Xeon] Up to 5600 MT/s [4th Gen Intel Xeon] Up to 4800 MT/s [Intel Xeon Max Series] Up to 4800 MT/s	Operating Properties	Operating: 10°C to 40°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing) *To ensure system stability and prevent condensation, when the relative humidity exceeds 50%, the coolant inlet temperature must be higher than the dry-bulb temperature and it should not exceed 45°C.
LAN	4 x 10/100/1000 Mbps Management LAN 1 x CMC Management LAN	Packaging Content	1 x H263-S62-LAW1 4 x CoolIT CPU cold plate loops 24 x Carriers 1 x 3-Section Rail kit
Video	Integrated in ASPEED® AST2600 x 4 - 4 x VGA ports	Ordering Part Numbers	6NH263S62DR000LBW1*
Storage	Front hot-swap: 24 x 2.5" Gen4 NVMe/SATA/SAS ^[1] Optional internal M.2: 4 x M.2 (2280/22110), PCIe Gen4 x4 ^[1] SAS card is required to support SAS drives.	Optional Parts	- M.2 riser card - CMTPO61: 9CMTPO61NR-00* - Ring topology kit (10-kit package): 6NH263S62S1000AAN11 - GIGABYTE CPU cold plate loop: 25H26-3S62000-E01X (QPA:4) - GIGABYTE 2U4N Manifold: 25H27-3Z80000-E07X (1 set per rack) - CoolIT leak sensor board: 6NH263S62S1000LAN11 (QPA:4)
RAID	Intel® SATA RAID 0/1/10/5 Onboard VROC key header		



Learn more at: <https://www.gigabyte.com/Enterprise>

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